

Supporting information

Mask-less soft lithography for fabricating micro- and nanoscale Ag structures *via* solid-state electrochemical etching using polymer electrolyte membrane for optoelectronic and sensing applications

Tatsuya Fujii¹, Daishi Hakozaiki¹, Atsuki Tsuji¹, Masaru Takizawa², and Junji Murata^{1,*}

¹Department of Mechanical Engineering, Ritsumeikan University

²Department of Physical Sciences, Ritsumeikan University

Keywords: nano-patterning, imprint lithography, solid-state electrochemical etching, polymer electrolyte membrane, flexible transparent electroconductive membrane, SERS

*Corresponding author

murata-j@fc.ritsumei.ac.jp

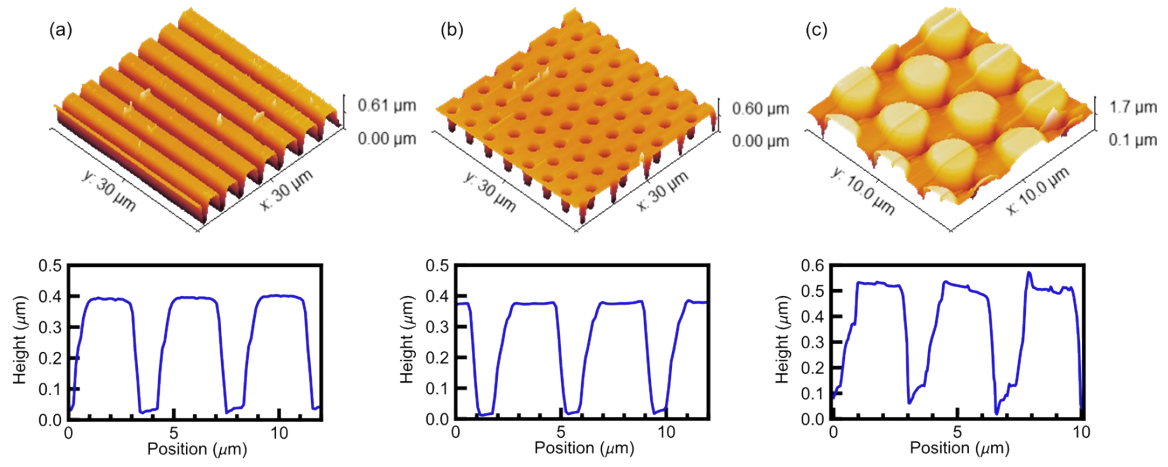


Fig. S1 AFM observations of the master molds containing (a) line and space (L&S), (b) pillar, and (c) hole structures with a pattern resolution of 2 μm

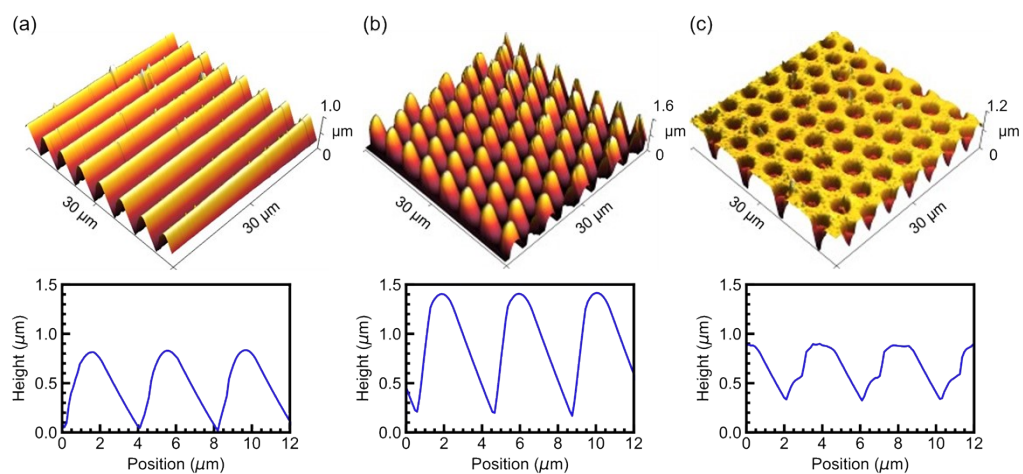


Fig. S2 AFM observations of the prepared PEM stamps containing (a) L&S, (b) pillar, and (c) hole structures with a pattern resolution of 2 μm

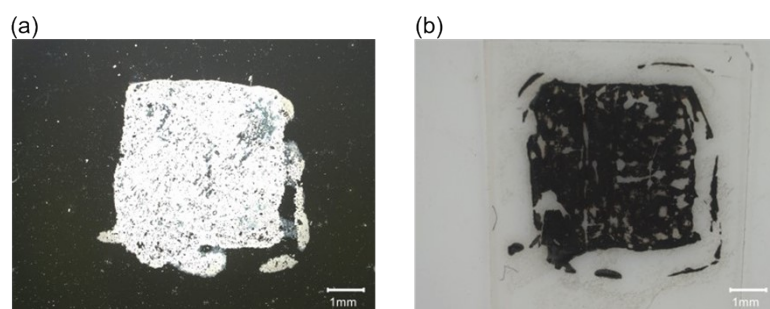


Fig. S3 Optical micrographs of (a) the Ag surface and (b) the PEM after the electrochemical measurement. The Ag thin film was almost completely removed from the substrate in the contact area with the PEM.

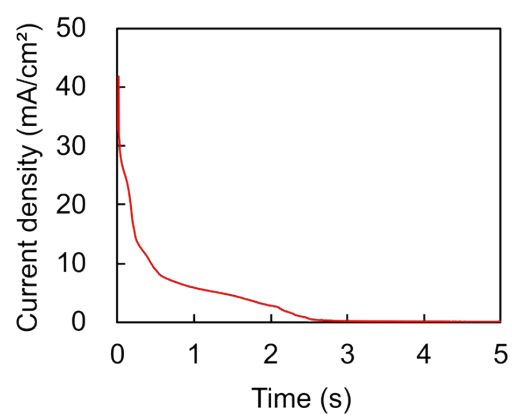


Fig. S4 Chronoamperometry (CA) profile of the solid-state electrochemical etching using the wet PEM stamp (2 μm hole) under a bias voltage of 1.2 V.

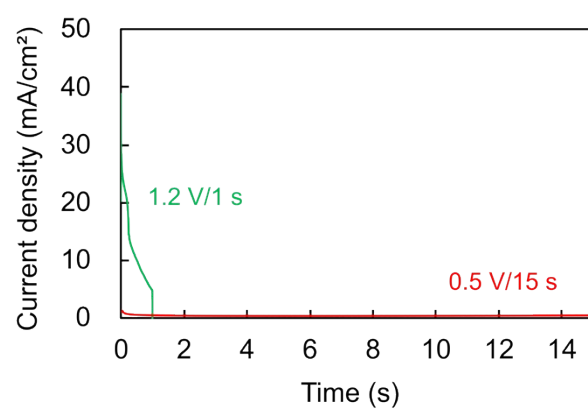


Fig. S5 Dependence of the electrolytic bias voltage on the CA profile.

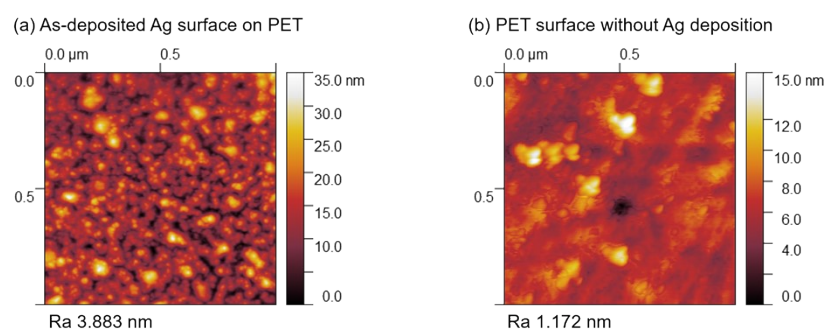


Fig. S6 AFM images of (a) as-deposited Ag surface on PET and (b) PET surface without Ag deposition.